

Global System in Package (SiP) Technology Market 2024 by Company, Regions, Type and Application, Forecast to 2030

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Abstracts

According to our (Global Info Research) latest study, the global System in Package (SiP) Technology market size was valued at USD million in 2023 and is forecast to a readjusted size of USD million by 2030 with a CAGR of % during review period.

SiP is a packaging technology, which contains multiple die in a single module. It is a mixture of various integrated circuits in a compact size, which further reduces the cost to develop and assemble a printed circuit board (PCB). SiP dies can be stacked vertically or tiled horizontally with standard off-chip wire bonds or solder bumps.

The global market for semiconductor was estimated at US\$ 579 billion in the year 2022, is projected to US\$ 790 billion by 2029, growing at a CAGR of 6% during the forecast period. Although some major categories are still double-digit year-over-year growth in 2022, led by Analog with 20.76%, Sensor with 16.31%, and Logic with 14.46% growth, Memory declined with 12.64% year over year. The microprocessor (MPU) and microcontroller (MCU) segments will experience stagnant growth due to weak shipments and investment in notebooks, computers, and standard desktops. In the current market scenario, the growing popularity of IoT-based electronics is stimulating the need for powerful processors and controllers. Hybrid MPUs and MCUs provide real-time embedded processing and control for the topmost IoT-based applications, resulting in significant market growth. The Analog IC segment is expected to grow gradually, while demand from the networking and communications industries is limited. Few of the emerging trends in the growing demand for Analog integrated circuits include signal conversion, automotive-specific Analog applications, and power management. They drive the growing demand for discrete power devices.

The Global Info Research report includes an overview of the development of the System in Package (SiP) Technology industry chain, the market status of Consumer Electronics (2-D IC Packaging, 2.5-D IC Packaging), Automotive (2-D IC Packaging, 2.5-D IC Packaging), and key enterprises in developed and developing market, and analysed the cutting-edge technology, patent, hot applications and market trends of System in Package (SiP) Technology.

Regionally, the report analyzes the System in Package (SiP) Technology markets in key regions. North America and Europe are experiencing steady growth, driven by government initiatives and increasing consumer awareness. Asia-Pacific, particularly China, leads the global System in Package (SiP) Technology market, with robust domestic demand, supportive policies, and a strong manufacturing base.

Key Features:

The report presents comprehensive understanding of the System in Package (SiP) Technology market. It provides a holistic view of the industry, as well as detailed insights into individual components and stakeholders. The report analysis market dynamics, trends, challenges, and opportunities within the System in Package (SiP) Technology industry.

The report involves analyzing the market at a macro level:

Market Sizing and Segmentation: Report collect data on the overall market size, including the revenue generated, and market share of different by Type (e.g., 2-D IC Packaging, 2.5-D IC Packaging).

Industry Analysis: Report analyse the broader industry trends, such as government policies and regulations, technological advancements, consumer preferences, and market dynamics. This analysis helps in understanding the key drivers and challenges influencing the System in Package (SiP) Technology market.

Regional Analysis: The report involves examining the System in Package (SiP) Technology market at a regional or national level. Report analyses regional factors such as government incentives, infrastructure development, economic conditions, and consumer behaviour to identify variations and opportunities within different markets.

Market Projections: Report covers the gathered data and analysis to make future projections and forecasts for the System in Package (SiP) Technology market. This may

include estimating market growth rates, predicting market demand, and identifying emerging trends.

The report also involves a more granular approach to System in Package (SiP) Technology:

Company Analysis: Report covers individual System in Package (SiP) Technology players, suppliers, and other relevant industry players. This analysis includes studying their financial performance, market positioning, product portfolios, partnerships, and strategies.

Consumer Analysis: Report covers data on consumer behaviour, preferences, and attitudes towards System in Package (SiP) Technology. This may involve surveys, interviews, and analysis of consumer reviews and feedback from different by Application (Consumer Electronics, Automotive).

Technology Analysis: Report covers specific technologies relevant to System in Package (SiP) Technology. It assesses the current state, advancements, and potential future developments in System in Package (SiP) Technology areas.

Competitive Landscape: By analyzing individual companies, suppliers, and consumers, the report present insights into the competitive landscape of the System in Package (SiP) Technology market. This analysis helps understand market share, competitive advantages, and potential areas for differentiation among industry players.

Market Validation: The report involves validating findings and projections through primary research, such as surveys, interviews, and focus groups.

Market Segmentation

System in Package (SiP) Technology market is split by Type and by Application. For the period 2019-2030, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of value.

Market segment by Type

2-D IC Packaging

2.5-D IC Packaging

3-D IC Packaging

Market segment by Application

Consumer Electronics

Automotive

Telecommunication

Industrial System

Aerospace & Defense

Others (Traction & Medical)

Market segment by players, this report covers

NXP

Amkor Technology

ASE

Jiangsu Changjiang Electronics Technology (JCET)

Siliconware Precision Industries (SPIL)

United Test and Assembly Center (UTAC)

Hana Micron

Hella

IMEC

Inari Berhad

Infineon

ams

Apple

ARM

Fitbit

Fujitsu

GaN Systems

Huawei

Qualcomm

SONY

Market segment by regions, regional analysis covers

North America (United States, Canada, and Mexico)

Europe (Germany, France, UK, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, South Korea, India, Southeast Asia, Australia and Rest of Asia-Pacific)

South America (Brazil, Argentina and Rest of South America)

Middle East & Africa (Turkey, Saudi Arabia, UAE, Rest of Middle East & Africa)

The content of the study subjects, includes a total of 13 chapters:

Chapter 1, to describe System in Package (SiP) Technology product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top players of System in Package (SiP) Technology, with revenue, gross margin and global market share of System in Package (SiP) Technology from 2019 to 2024.

Chapter 3, the System in Package (SiP) Technology competitive situation, revenue and global market share of top players are analyzed emphatically by landscape contrast.

Chapter 4 and 5, to segment the market size by Type and application, with consumption value and growth rate by Type, application, from 2019 to 2030.

Chapter 6, 7, 8, 9, and 10, to break the market size data at the country level, with revenue and market share for key countries in the world, from 2019 to 2024. and System in Package (SiP) Technology market forecast, by regions, type and application, with consumption value, from 2025 to 2030.

Chapter 11, market dynamics, drivers, restraints, trends and Porters Five Forces analysis.

Chapter 12, the key raw materials and key suppliers, and industry chain of System in Package (SiP) Technology.

Chapter 13, to describe System in Package (SiP) Technology research findings and conclusion.

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